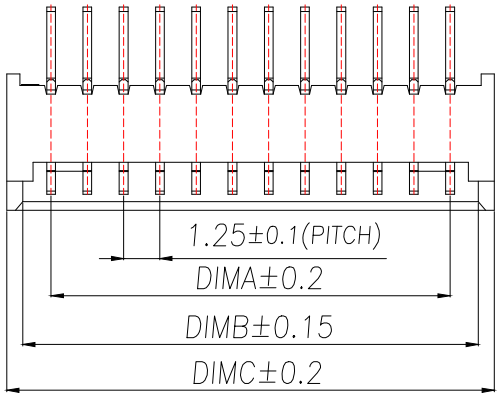
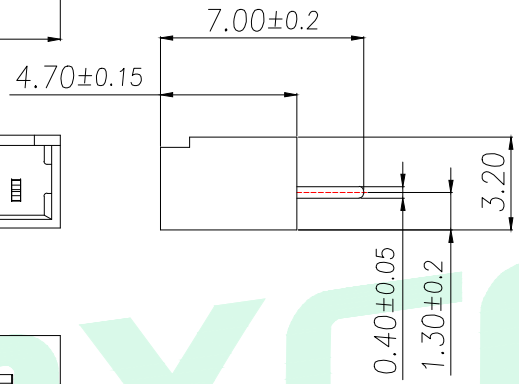
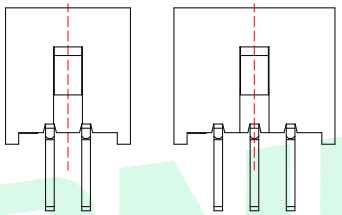
REV.	DESCRIPTION	ECN NO.	NAME	DATE

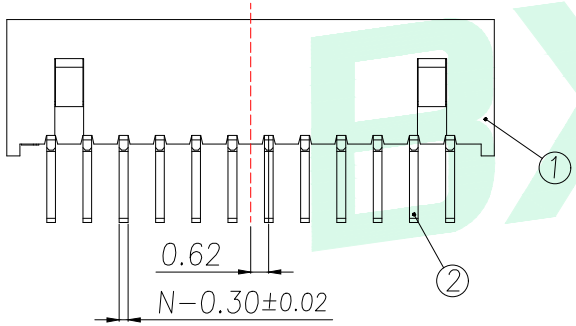


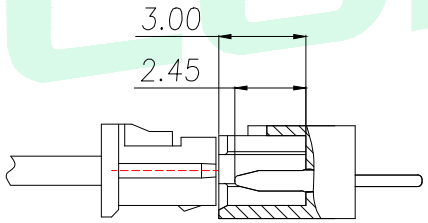
序号	品名	材质
1	1.25 Pitch S/T Wire To Board Housing DIP(H=4.7)	PA66 UL94V-2 Red
2	1.25 Pitch S/T Wire To Board Terminal DIP(H=4.7)	Copper Alloy/ Tin Plating

Part No	Pin	A	B	C
AF-MX1.25-2PZZ-R2	2	1.25	3.20	4.30
AF-MX1.25-3PZZ-R2	3	2.50	4.45	5.55
AF-MX1.25-4PZZ-R2	4	3.75	5.70	6.80
AF-MX1.25-5PZZ-R2	5	5.00	6.95	8.05
AF-MX1.25-6PZZ-R2	6	6.25	8.20	9.30
AF-MX1.25-7PZZ-R2	7	7.50	9.45	10.55
AF-MX1.25-8PZZ-R2	8	8.75	10.70	11.80
AF-MX1.25-9PZZ-R2	9	10.00	11.95	13.05
AF-MX1.25-10PZZ-R2	10	11.25	13.20	14.30
AF-MX1.25-11PZZ-R2	11	12.50	14.45	15.55
AF-MX1.25-12PZZ-R2	12	13.75	15.70	16.80
AF-MX1.25-13PZZ-R2	13	15.00	16.95	18.05
AF-MX1.25-14PZZ-R2	14	16.25	18.20	19.30
AF-MX1.25-15PZZ-R2	15	17.50	19.45	20.55
AF-MX1.25-16PZZ-R2	16	18.75	20.70	21.80
AF-MX1.25-17PZZ-R2	17	20.00	21.95	23.05
AF-MX1.25-18PZZ-R2	18	21.25	23.20	24.30
AF-MX1.25-19PZZ-R2	19	22.50	24.45	25.55
AF-MX1.25-20PZZ-R2	20	23.75	25.70	26.80

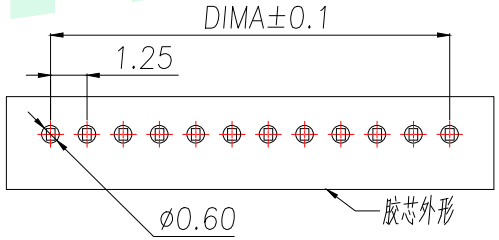



LOCK CONFIGURATION(锁扣位置)





SECTION A-A



适用线路板(PCB LAYOUT)

Technical Index:

1.The surface of the plastic parts should be smooth,no rough edges,no obvious shrinkage,defects,cracks and other phenomena)

2.Lock Configuration:2 to 3Pin is 1,≥4Pin is 2

3.Temperature range:-40°C~+85°C.

4.Rated voltage:125V,AC/DC.

5.Contact resistance:≤0.02Ω.

6.Insulation resistance:≥100MΩ

GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD	BXCONN®
DIM. TOL. x. ±0.50 x.x ±0.20 x.xx ±0.10 GENERAL ANGLE: x.° ±5° x.x° ±3° x.xx° ±1°	TITLE: 1.25 PITCH H4.7 S/T WIRE TO BOARD DIP CONN.	
	DWG. NO.: AF-MX1.25-NPZZ-R2 / CHECKED: MAX	
	PART NO.: AF-MX1.25-NPZZ-R2 / DRAWN: ELLA	
	UNIT: mm / SCALE: none / SHEET: 1of 1 / DWG. SIZE: A4 / LAYER: bxconn / APPROVED: WILL	